

FIG. 1A

PRIOR ART

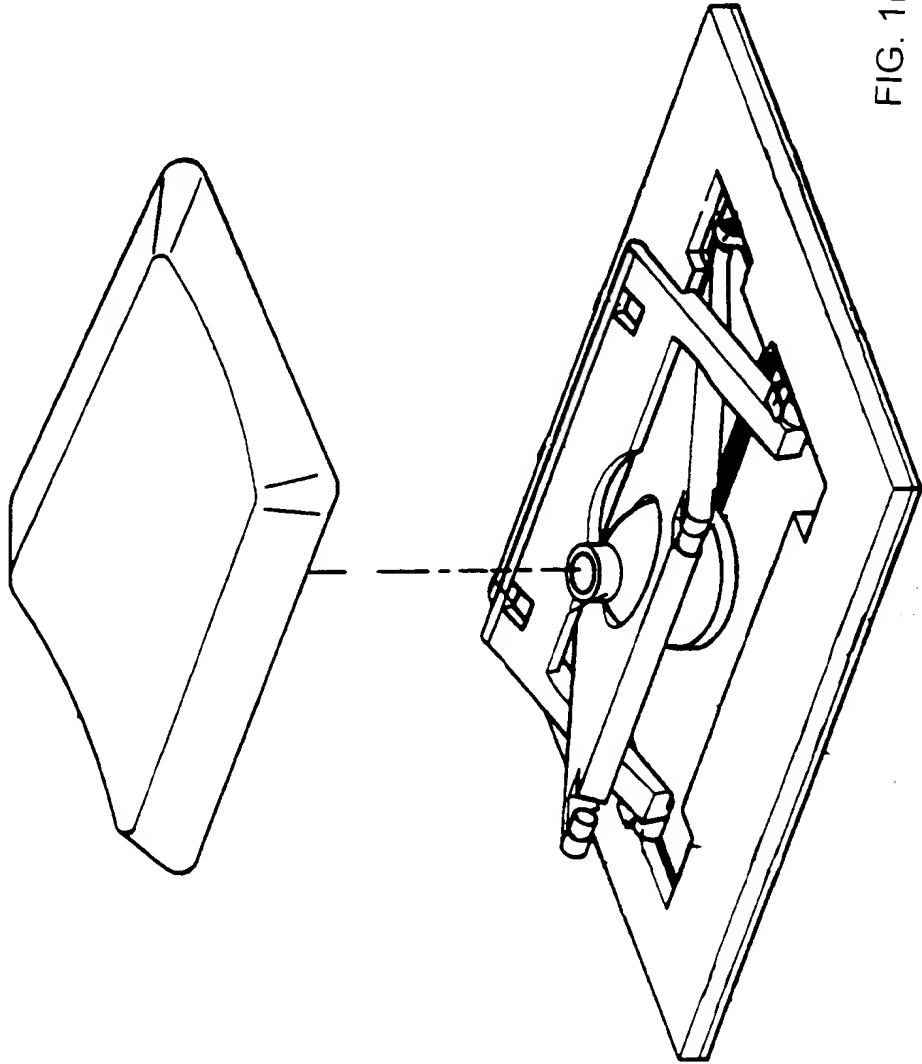


FIG. 1B

PRIOR ART

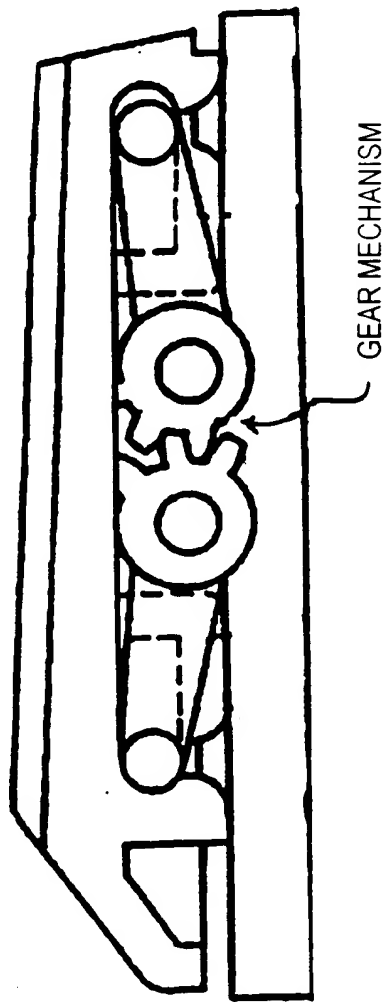
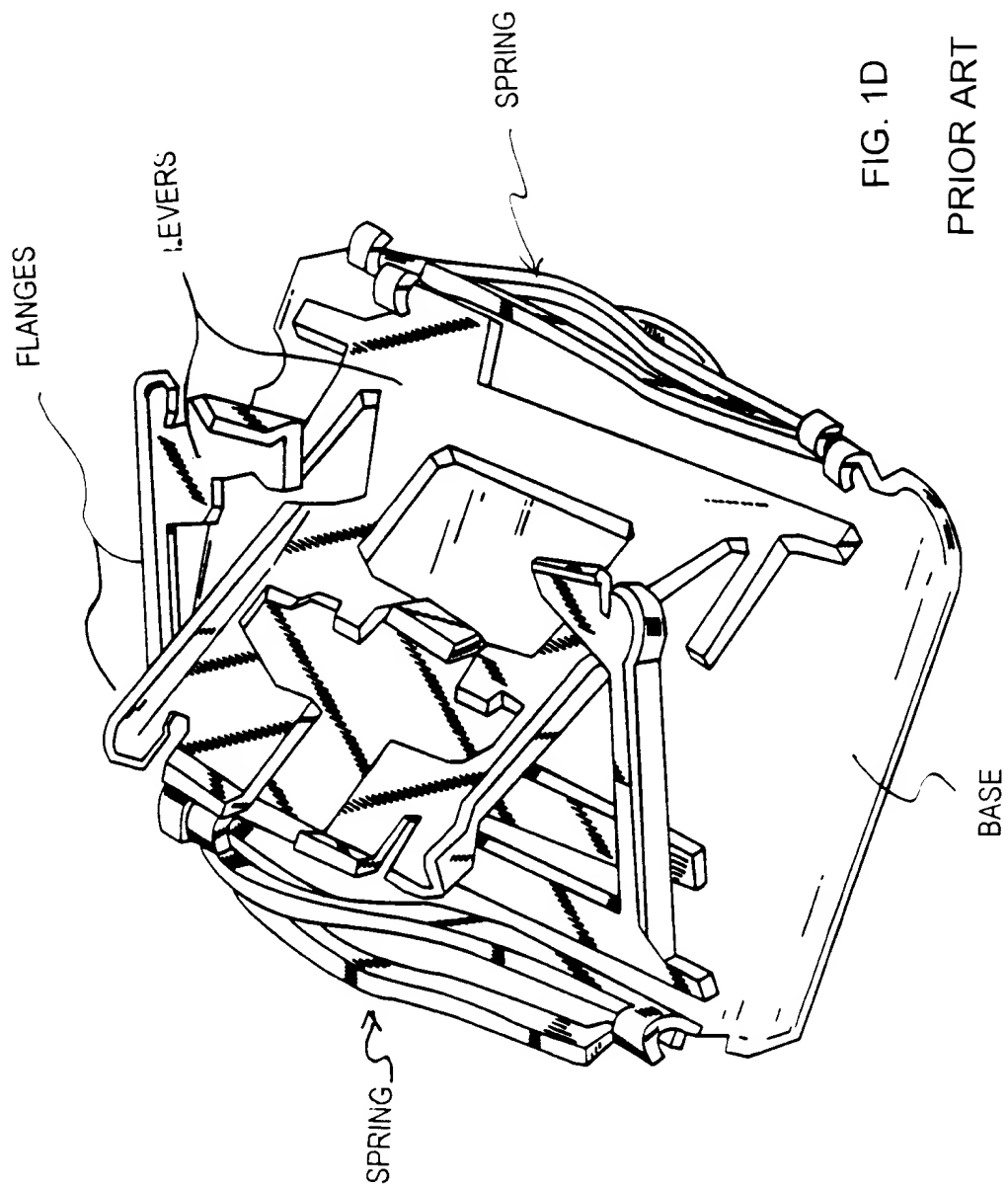


FIG. 1C

PRIOR ART



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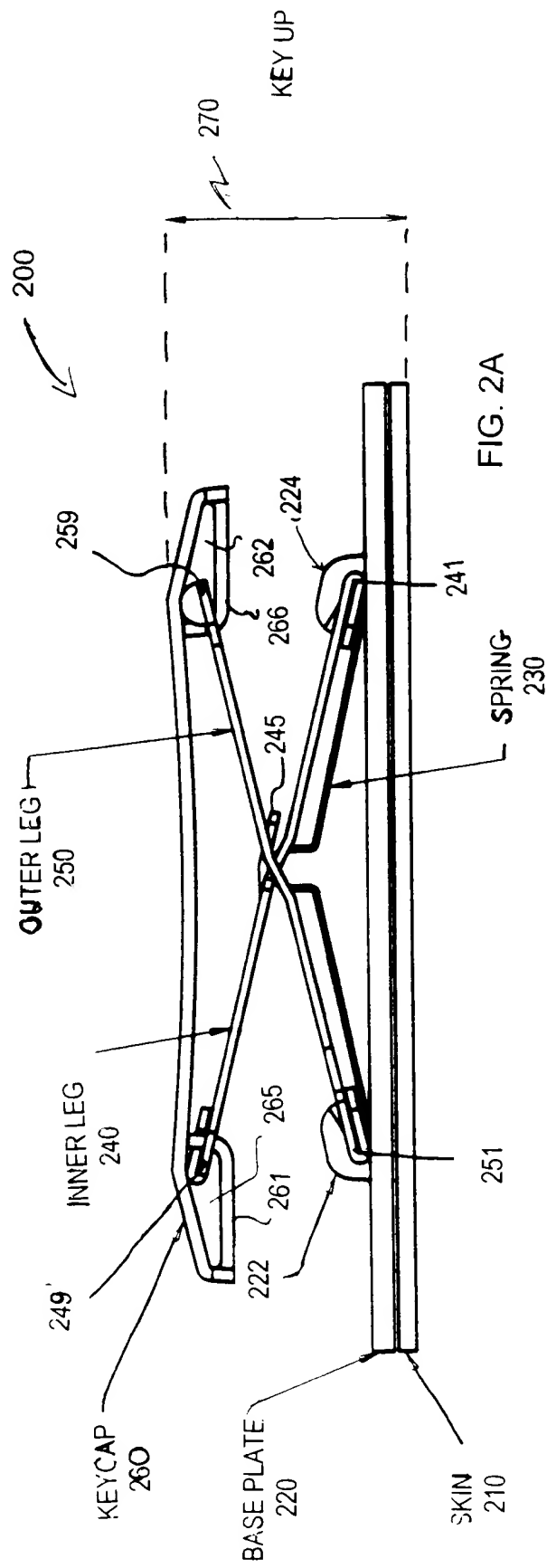


FIG. 2A



FIG. 2B

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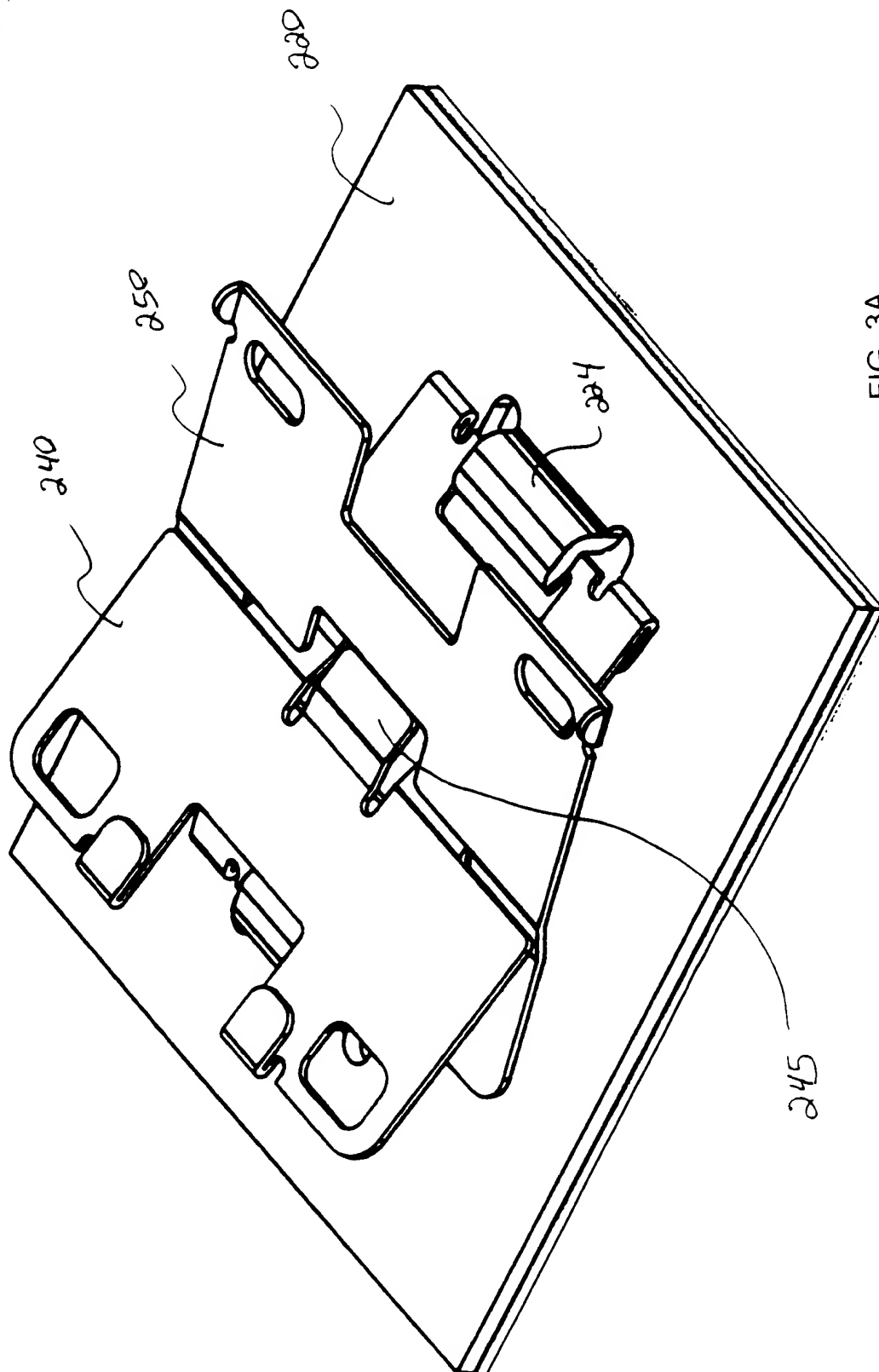
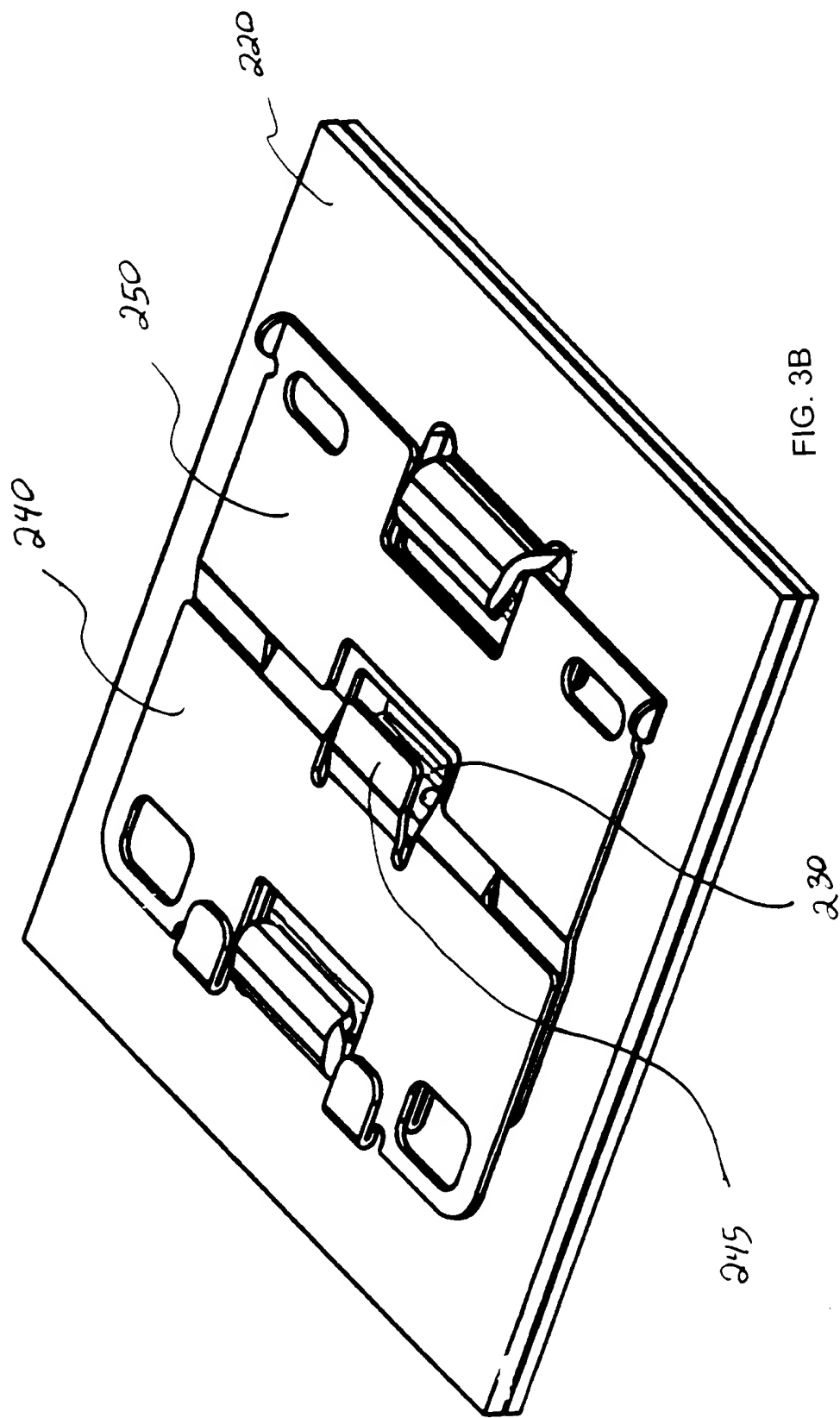


FIG. 3A

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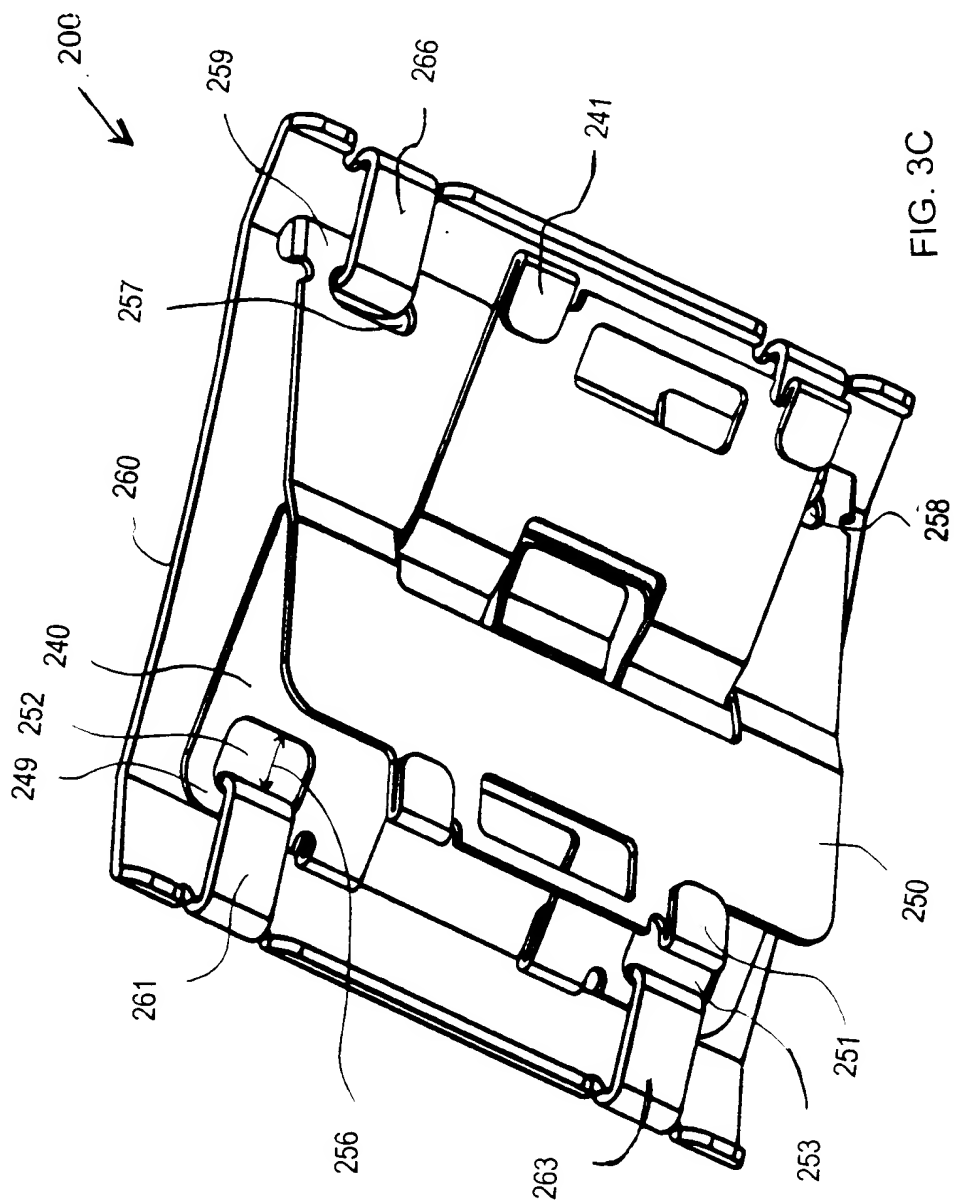


FIG. 3C



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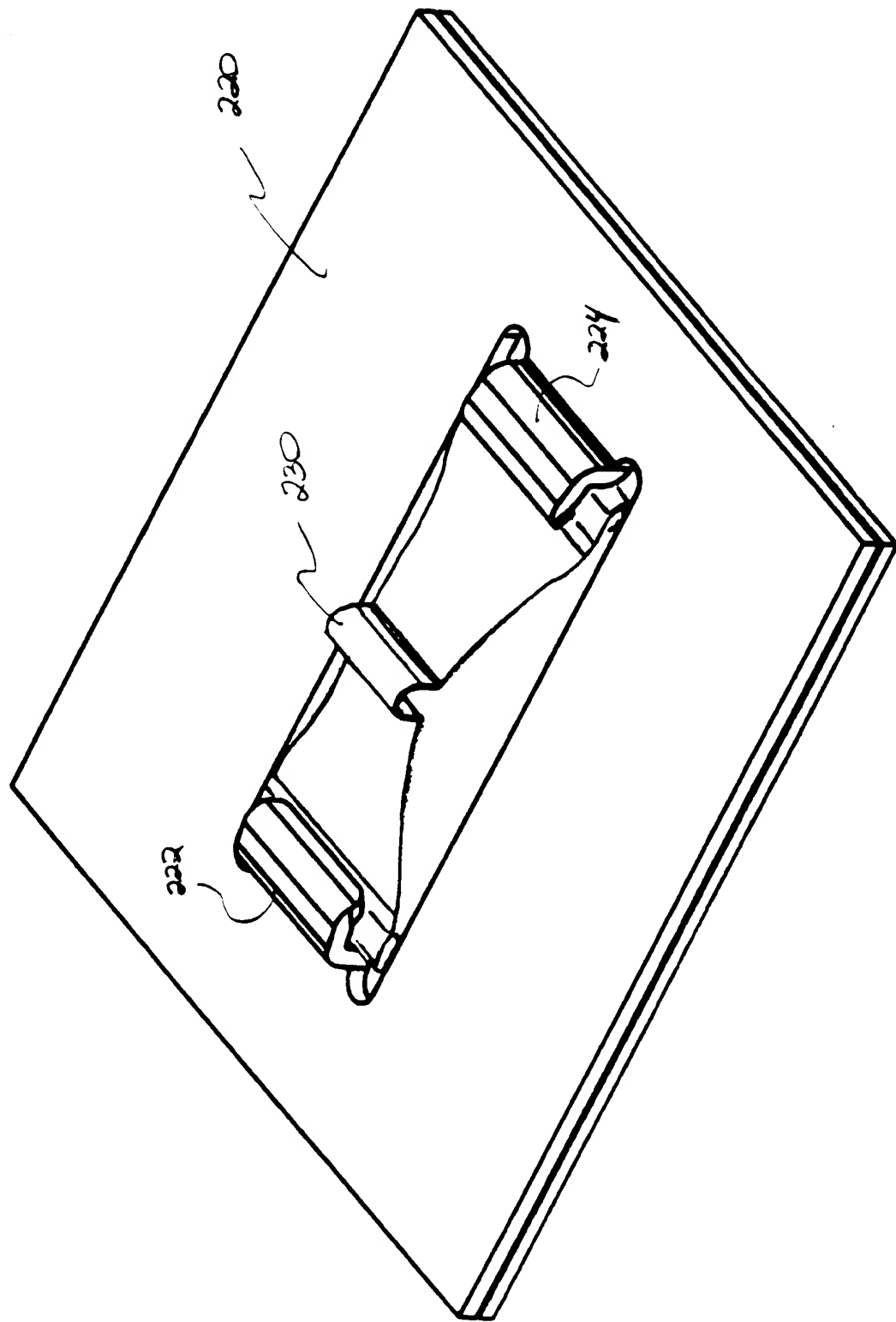
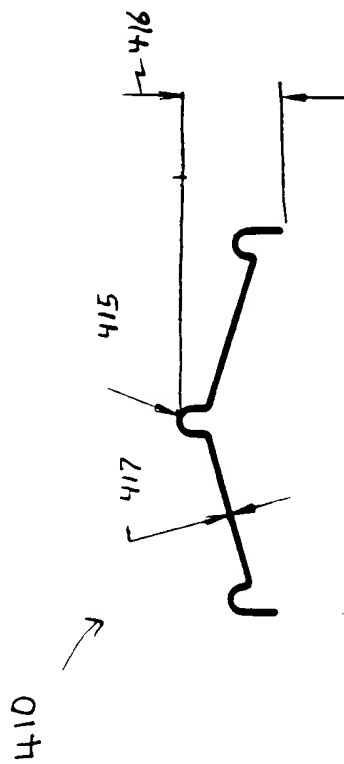
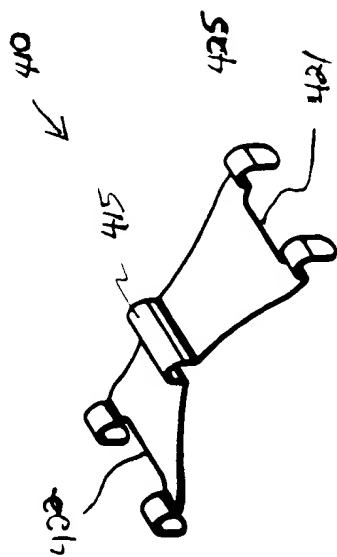
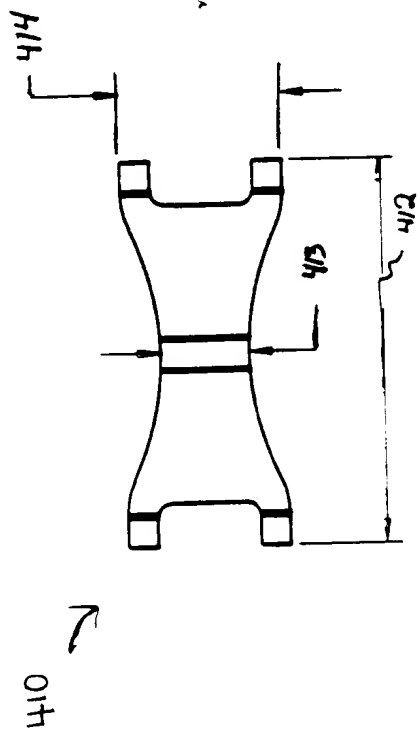


FIG. 3D



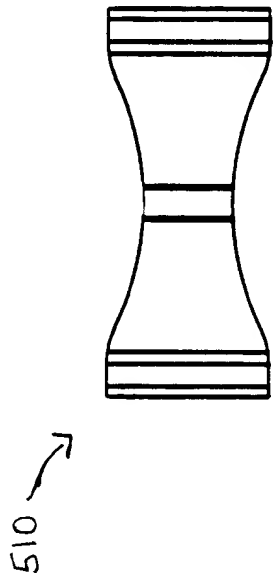


FIG. 5B

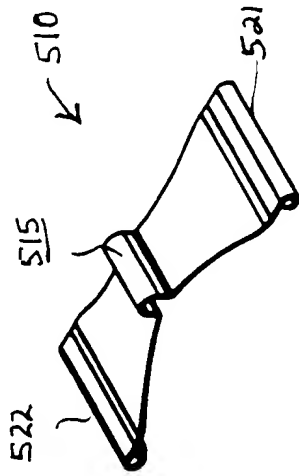


FIG. 5A

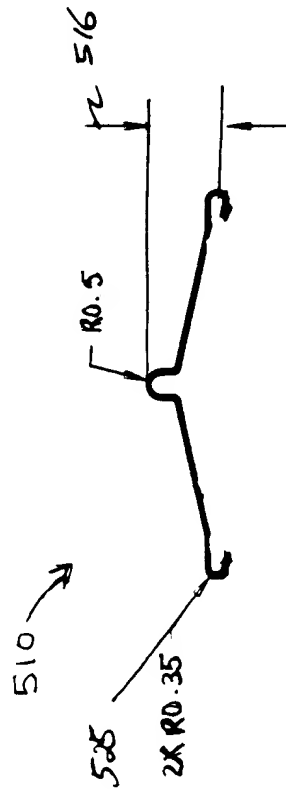


FIG. 5C

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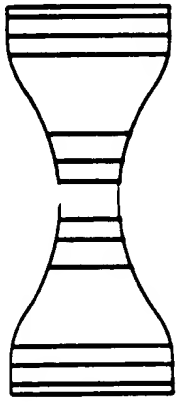


FIG. 6B

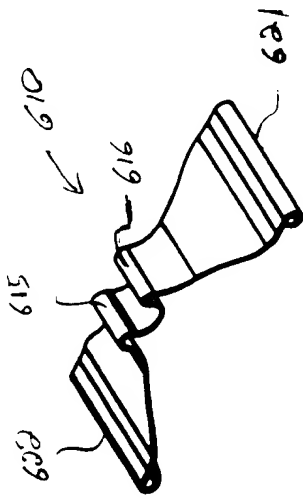


FIG. 6A

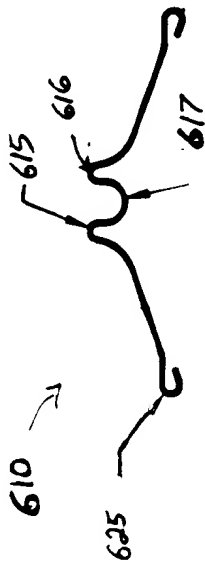


FIG. 6C

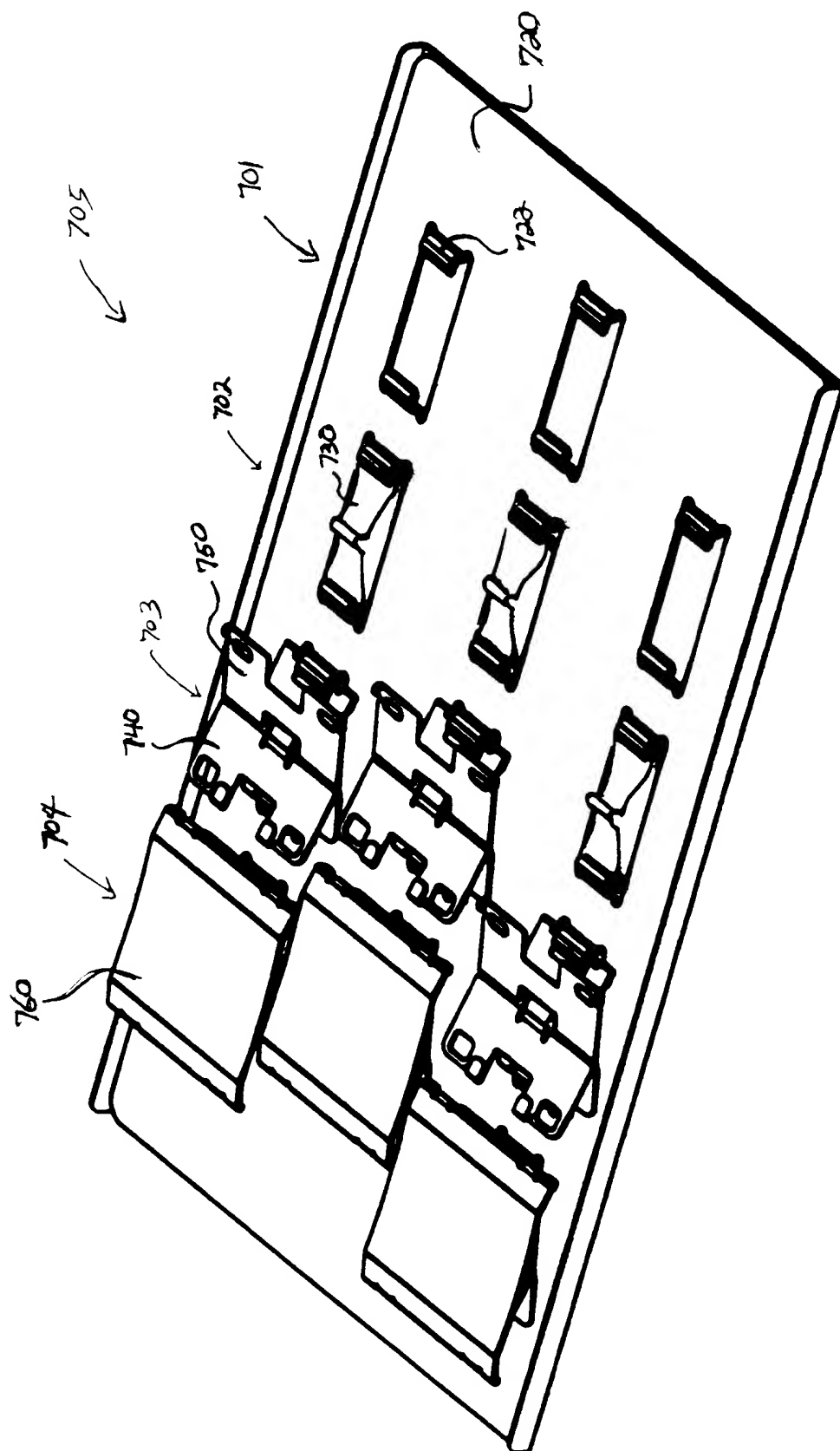


FIG. 7

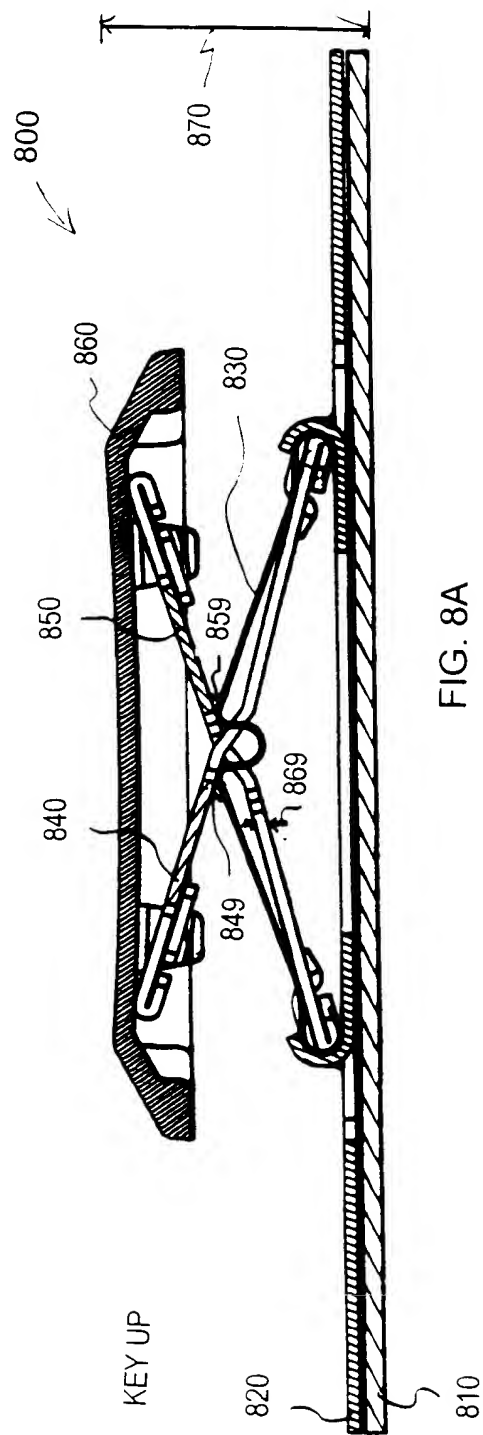


FIG. 8A

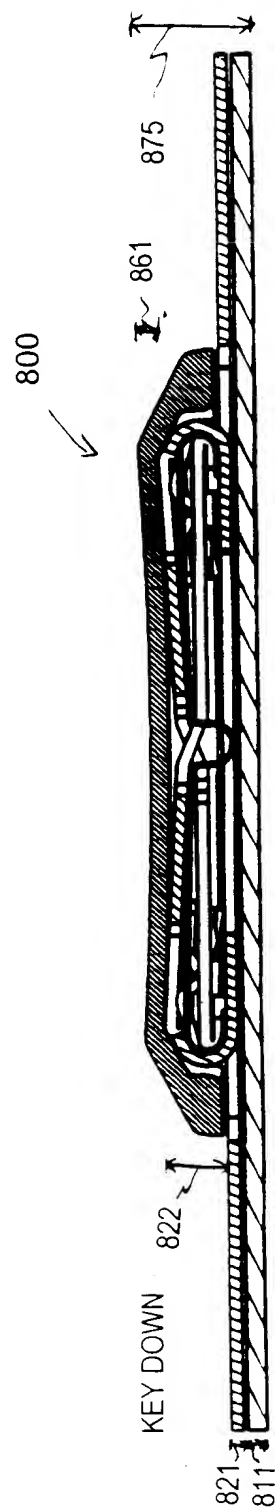


FIG. 8B

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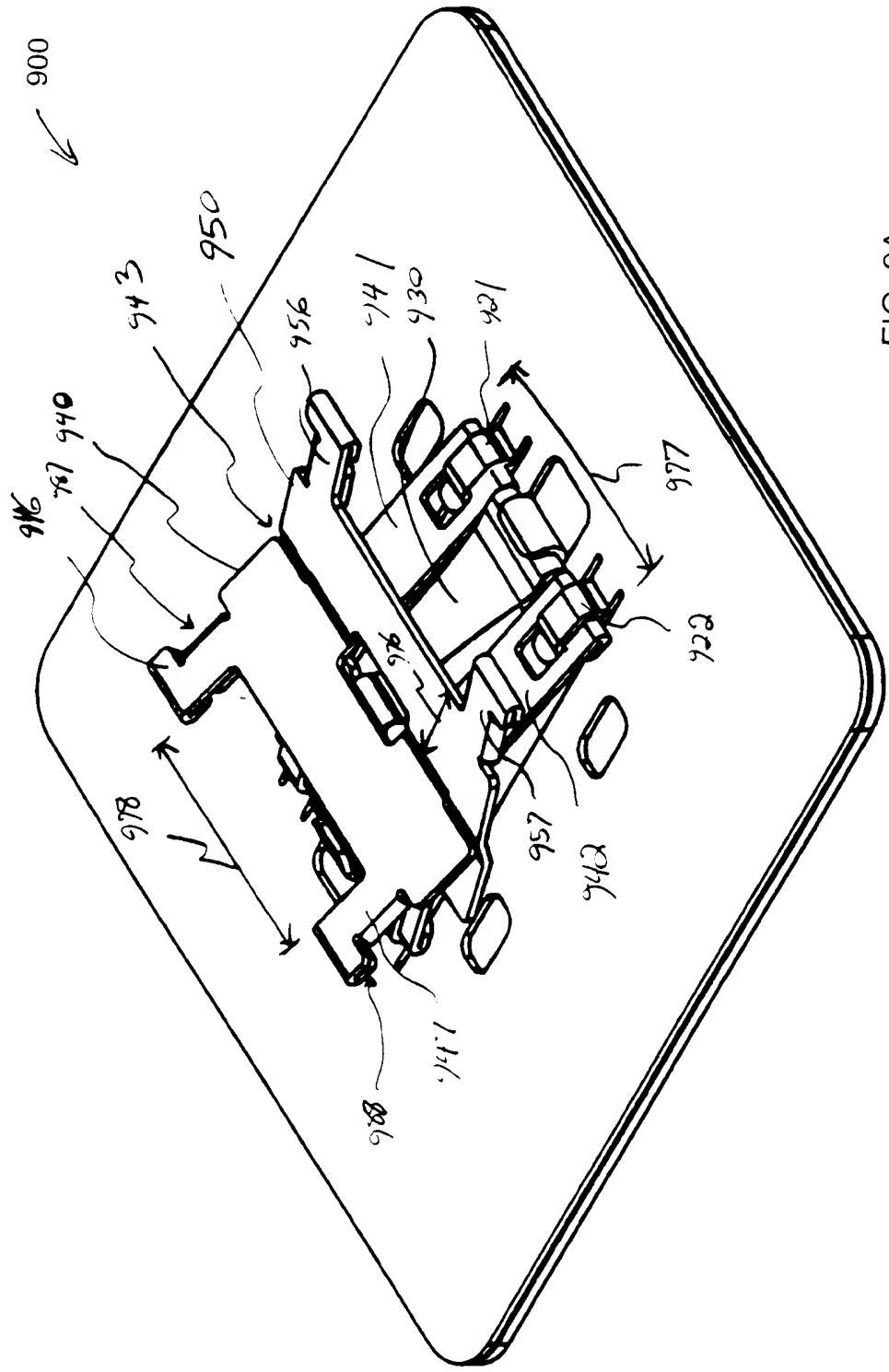


FIG. 9A

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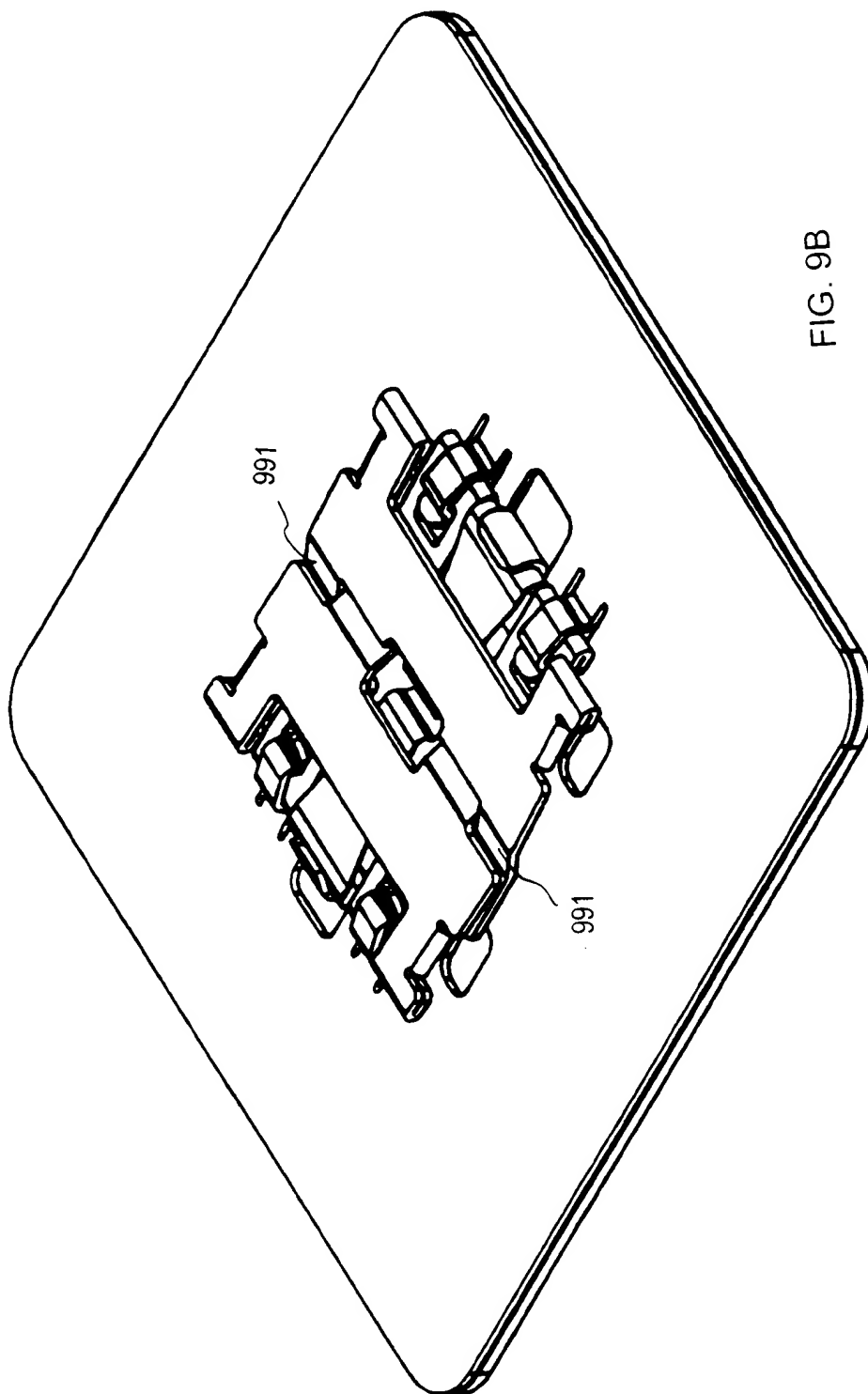


FIG. 9B



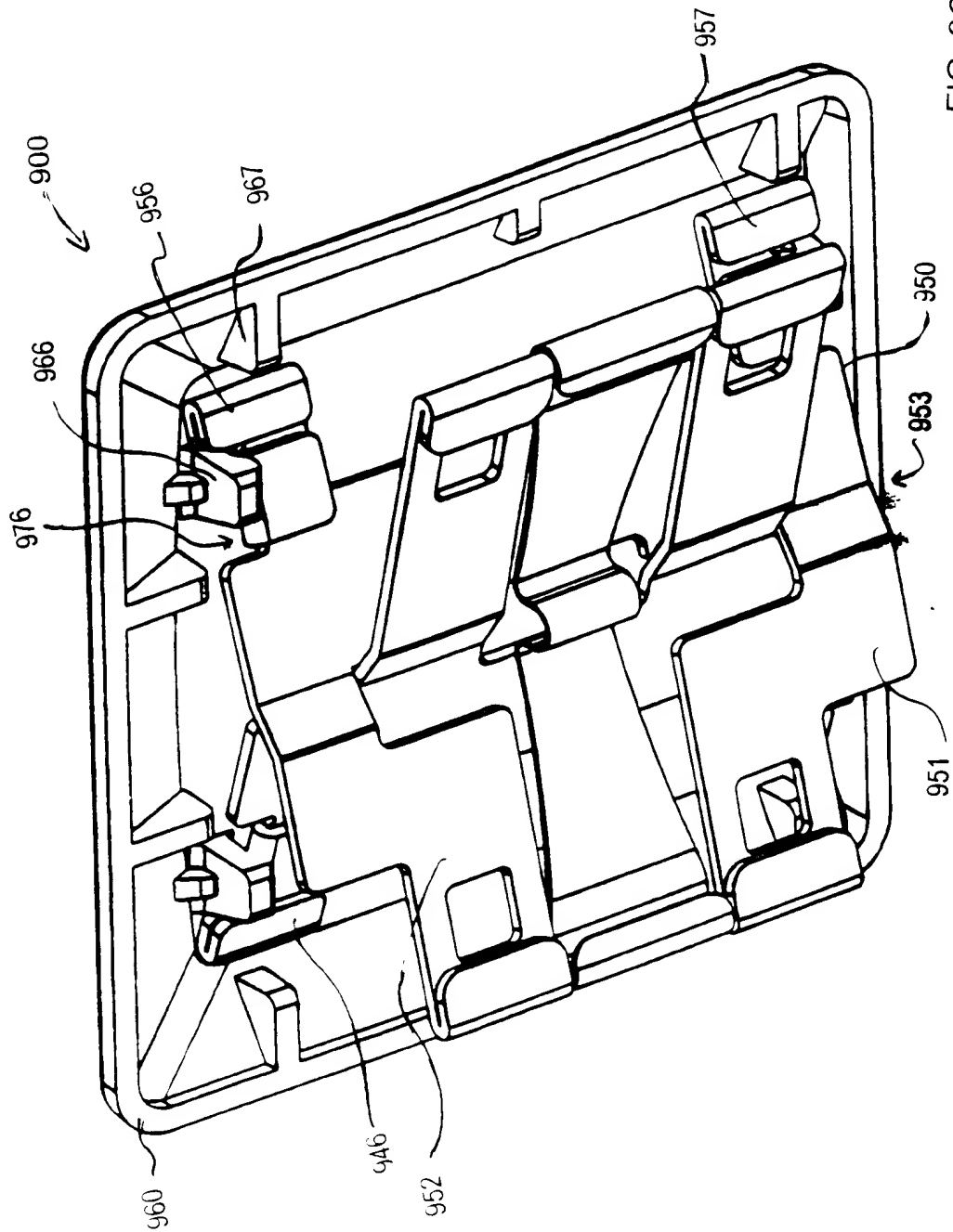


FIG. 9C

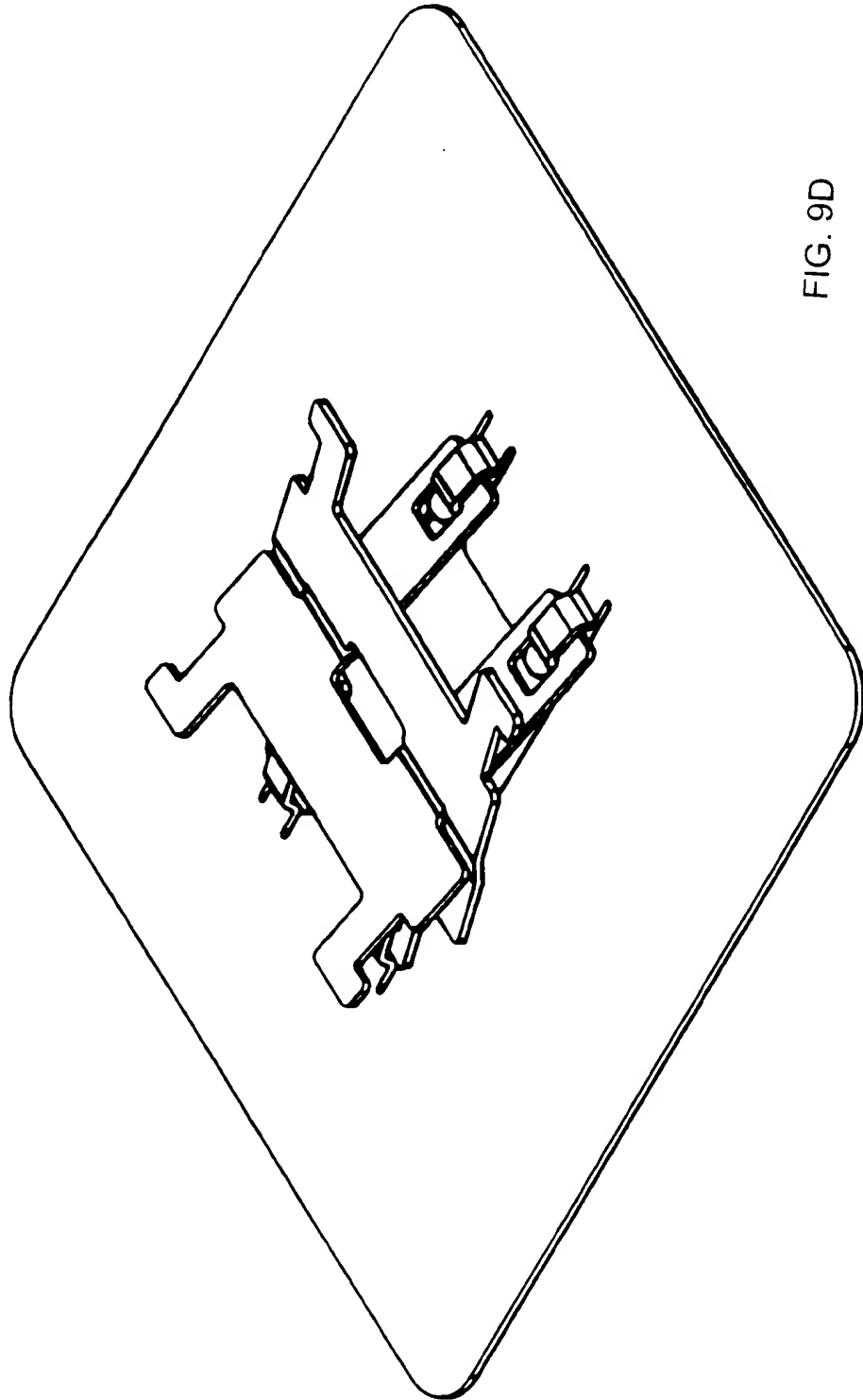


FIG. 9D

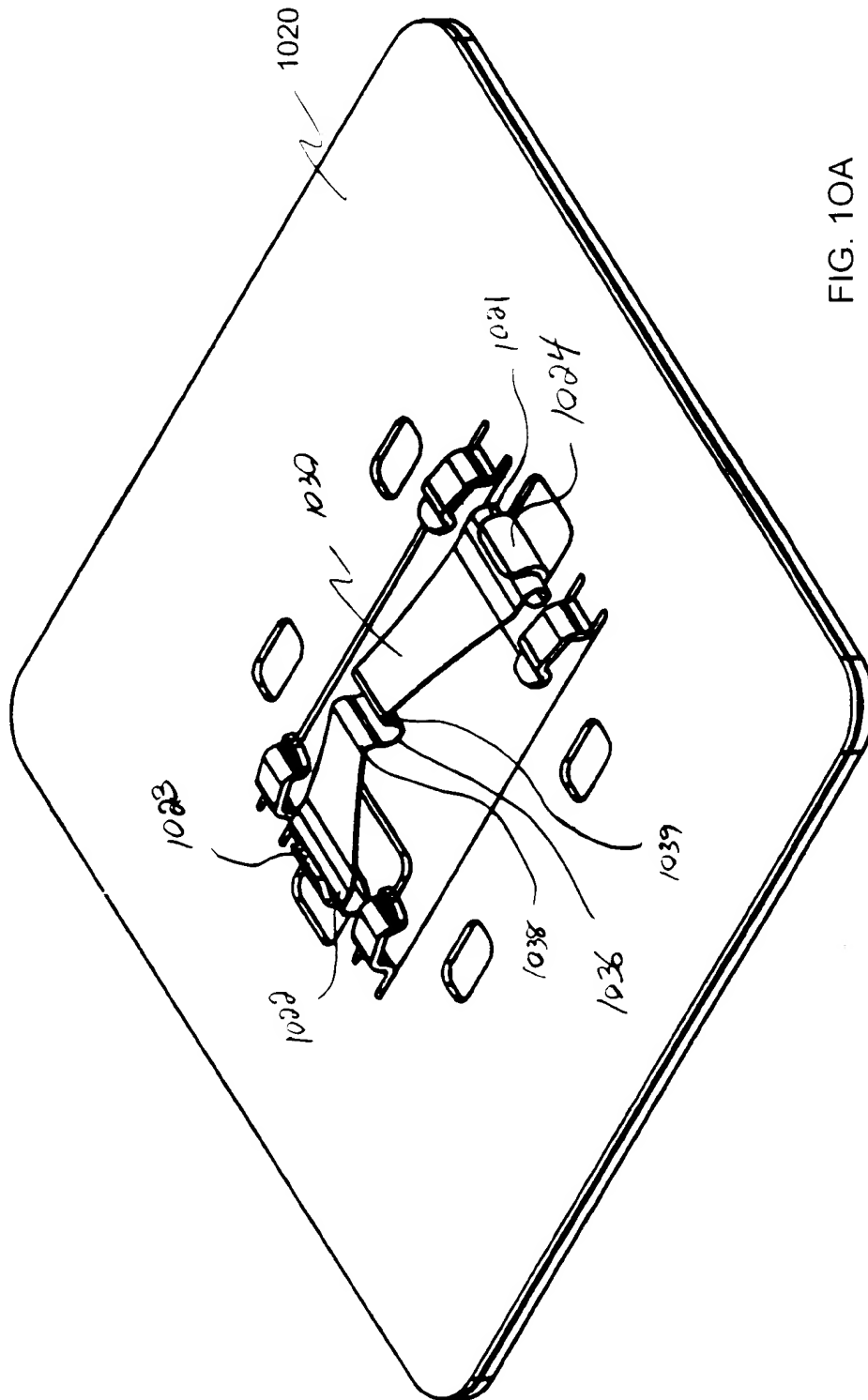


FIG. 10A

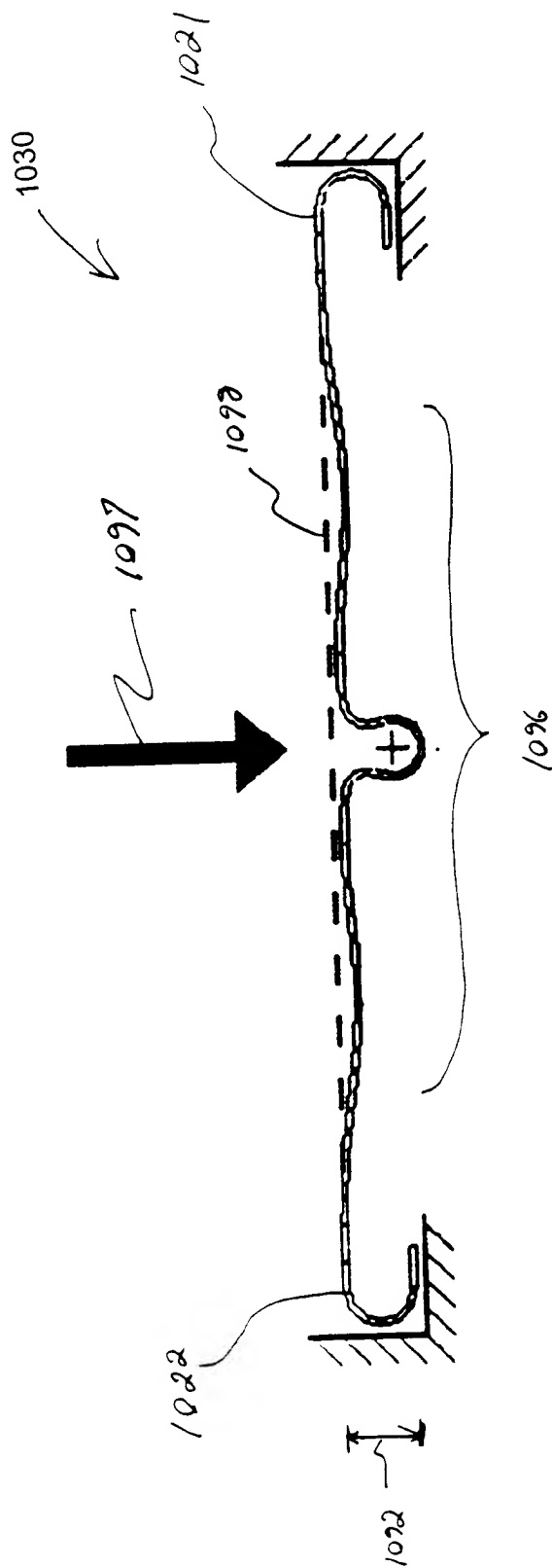


FIG. 10B

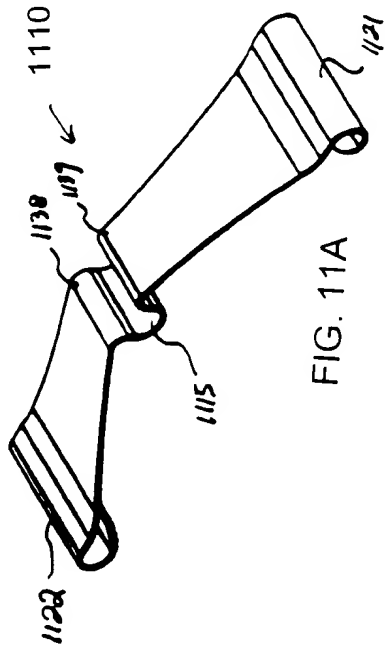


FIG. 11A

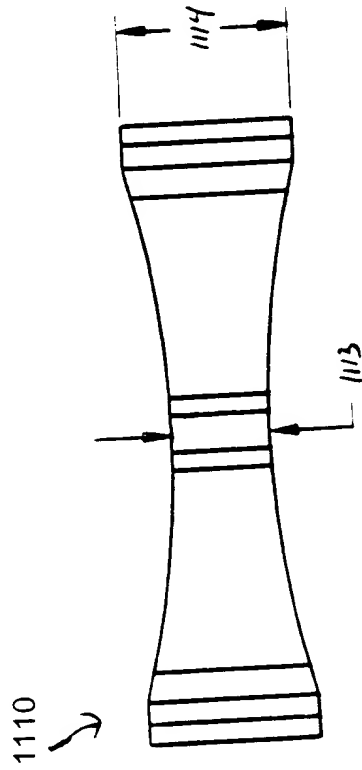


FIG. 11B

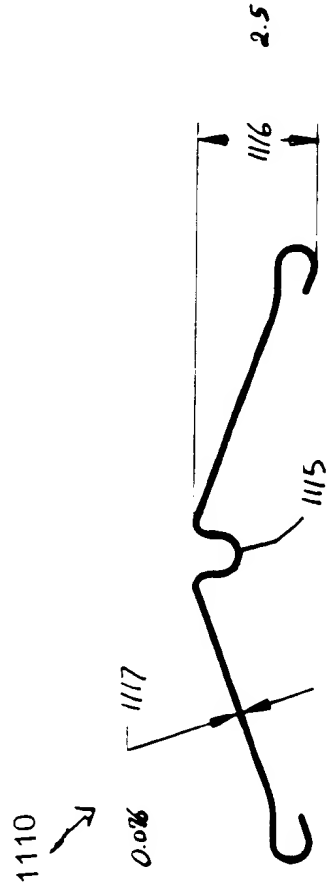
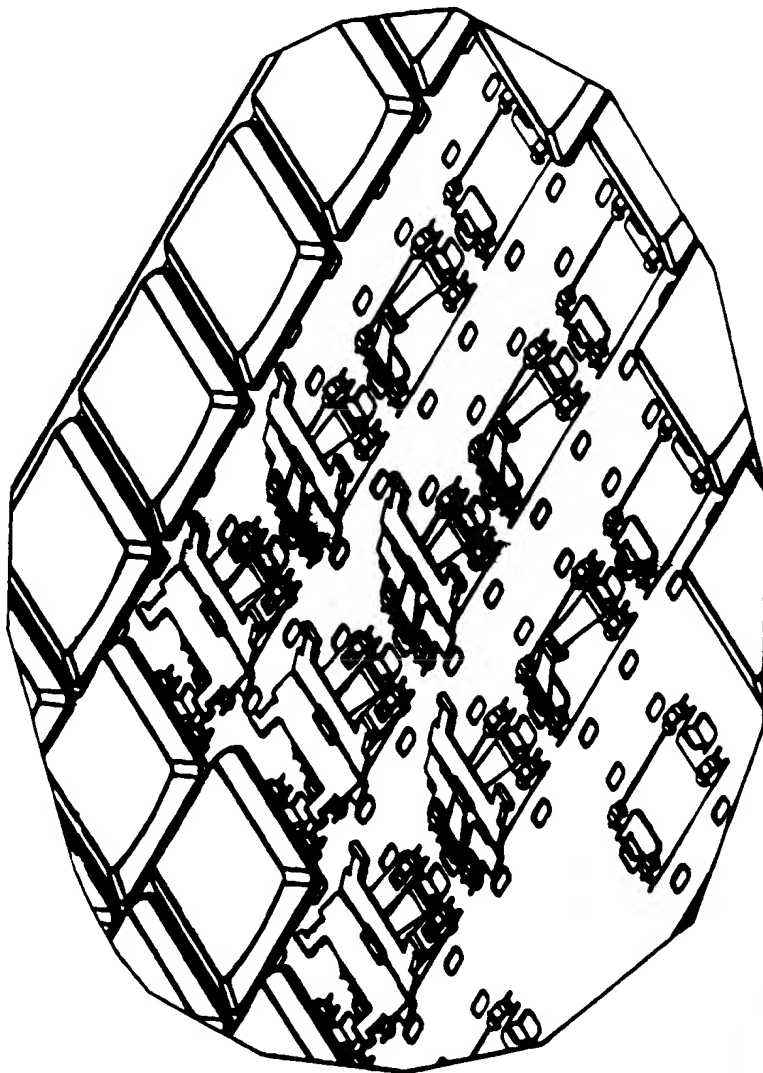
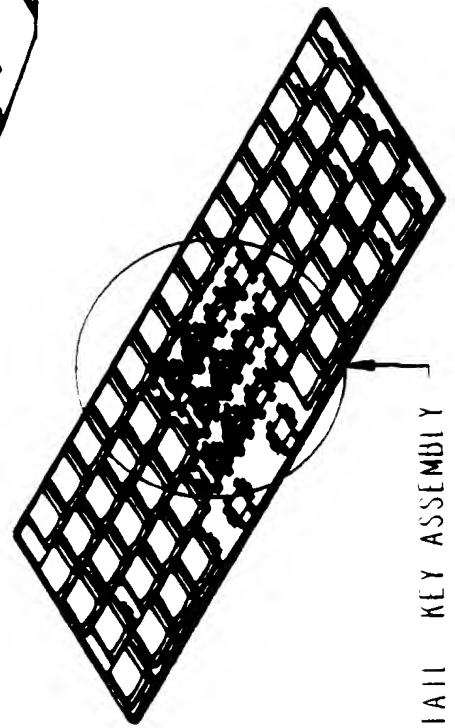


FIG. 11C

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DETAIL KEY ASSEMBLY



DETAIL KEY ASSEMBLY

FIG. 12

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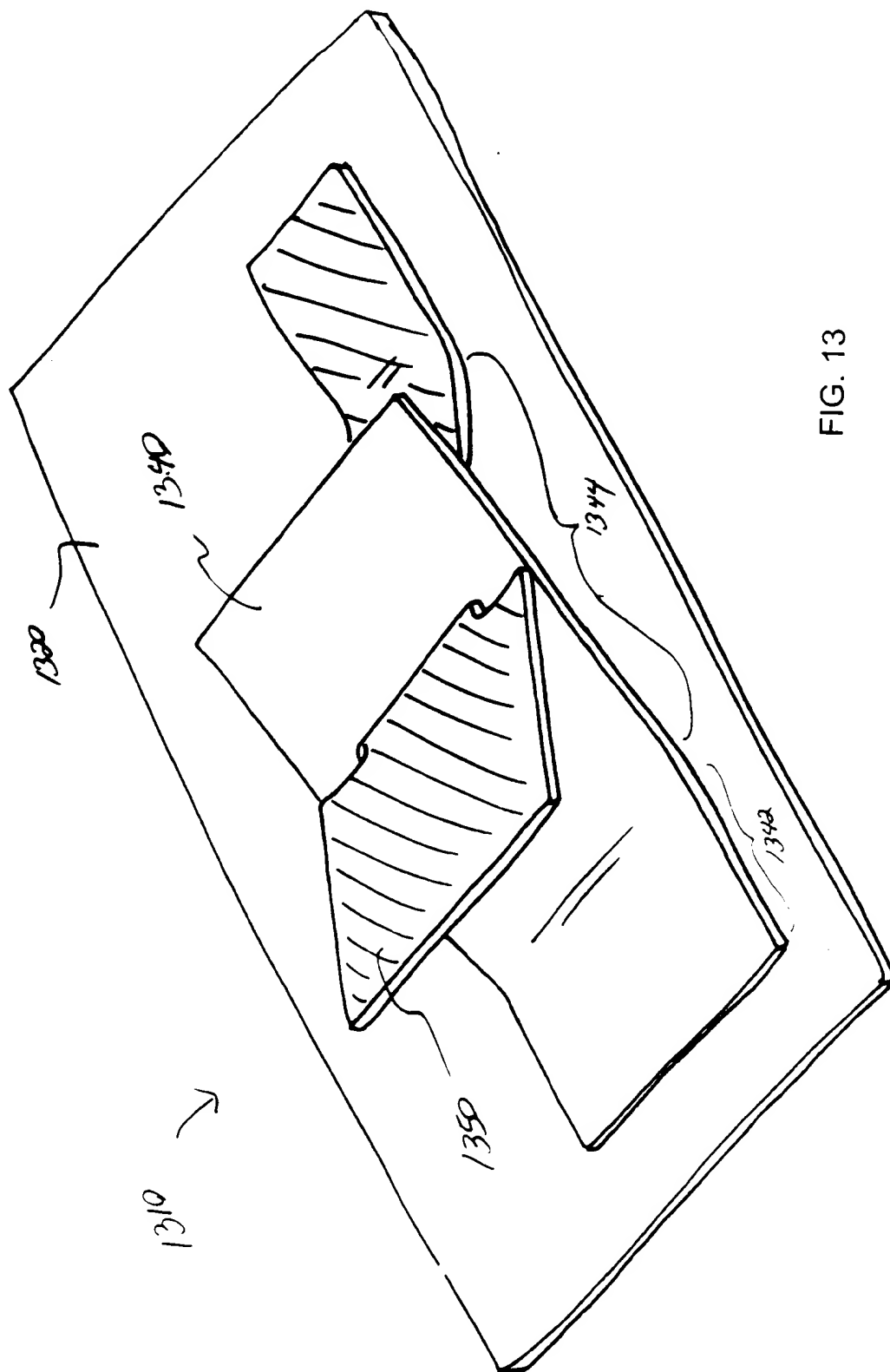


FIG. 13

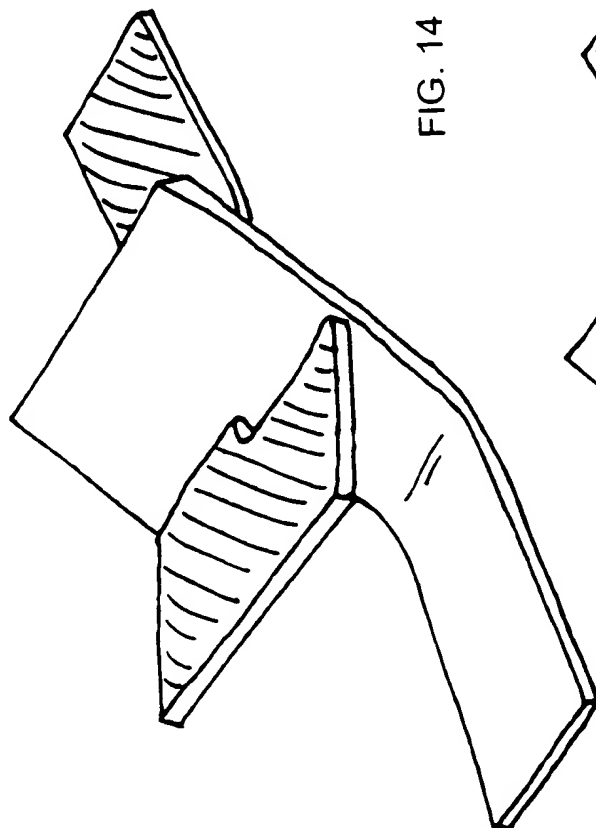


FIG. 14

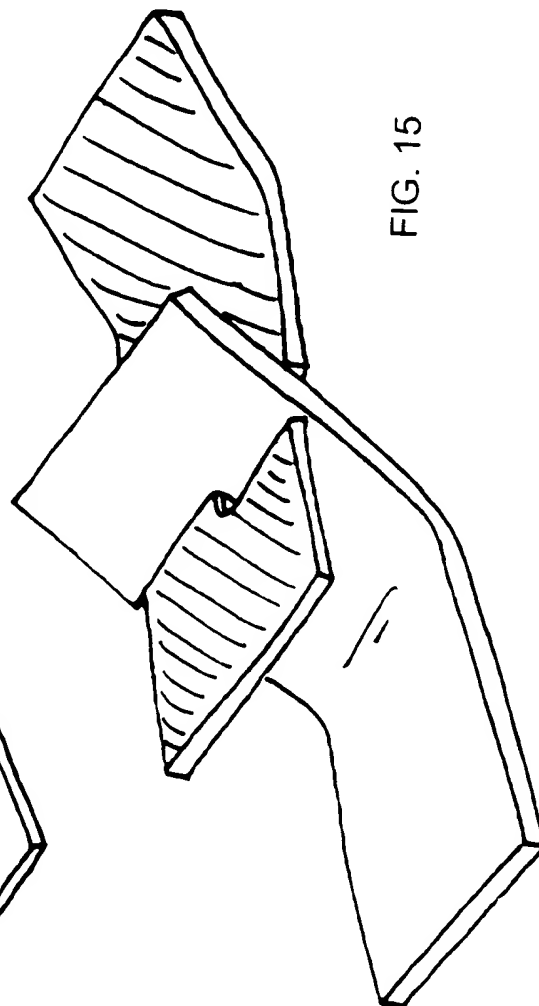


FIG. 15



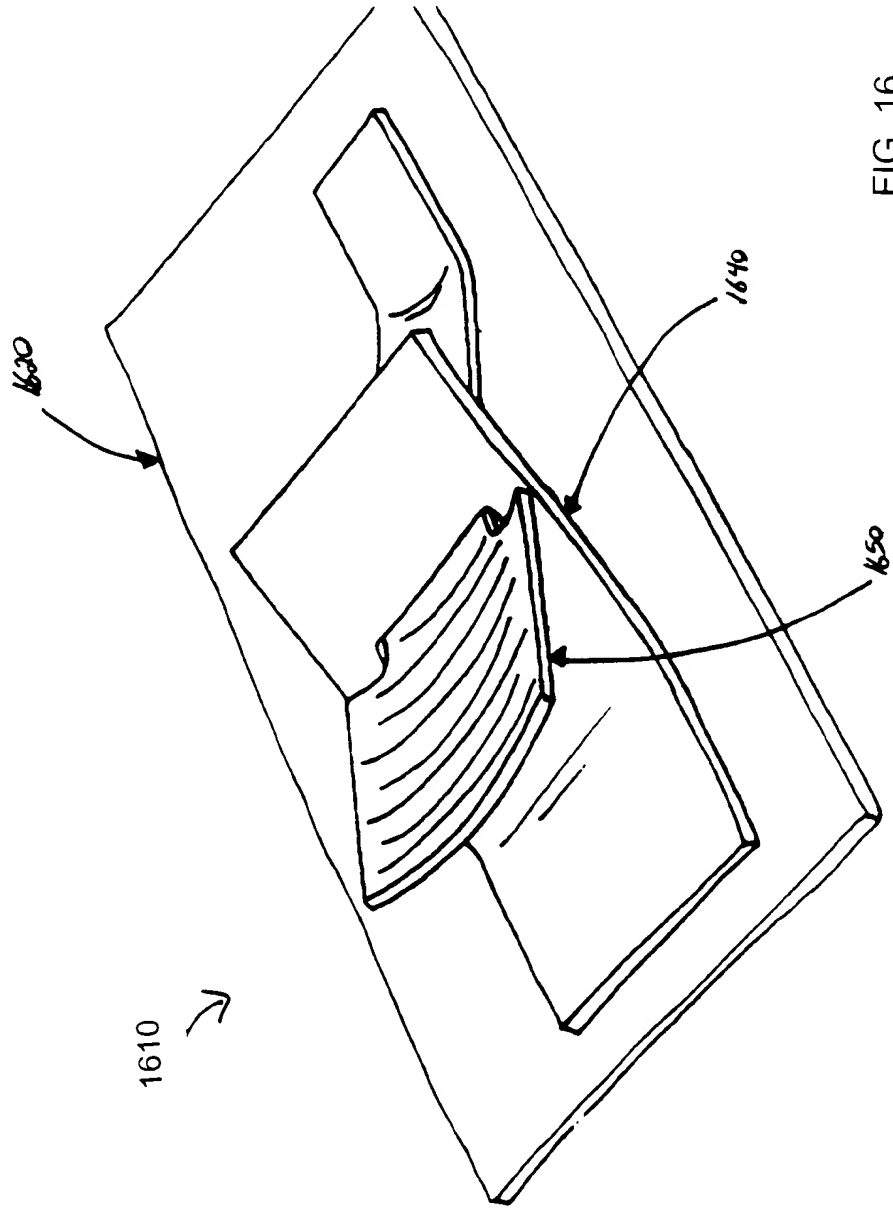


FIG. 16

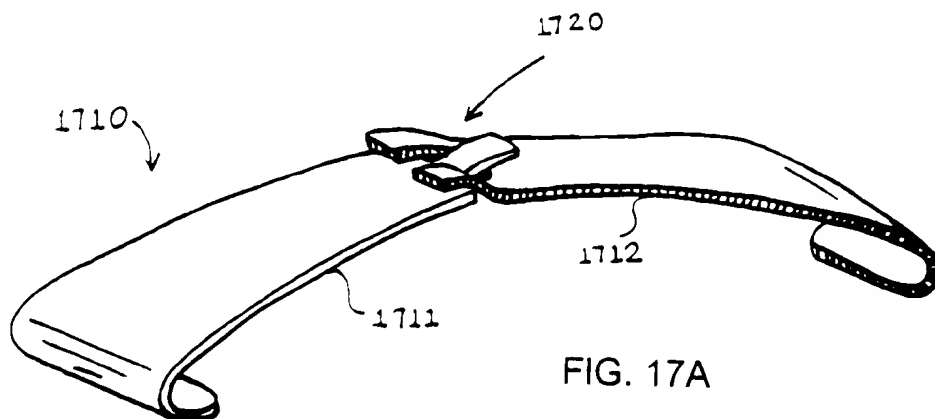


FIG. 17A

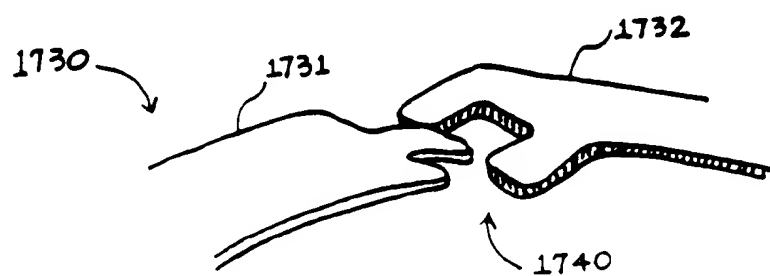


FIG. 17B

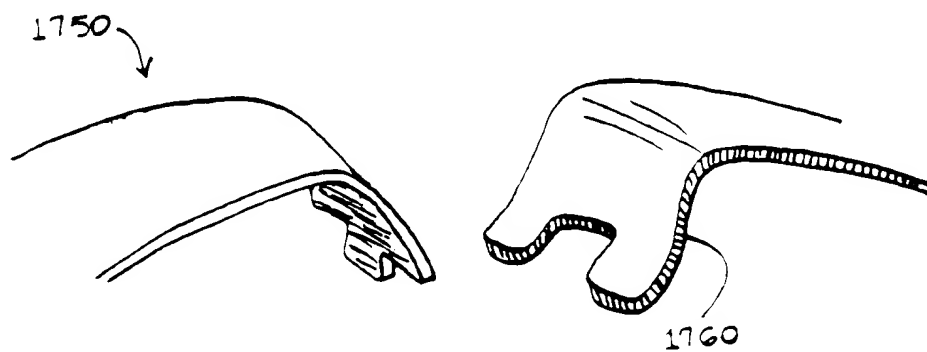


FIG. 17C

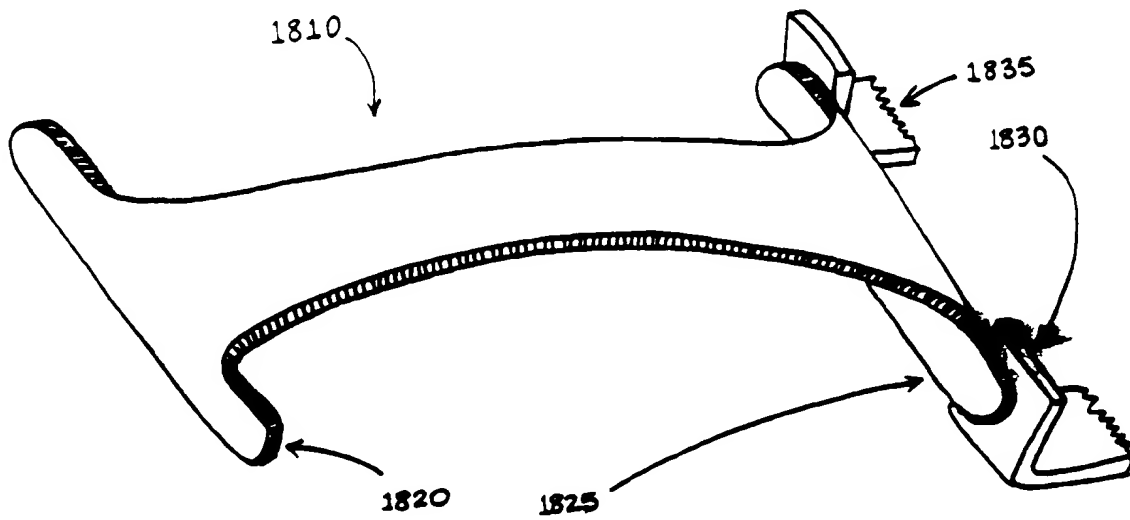


FIG. 18A

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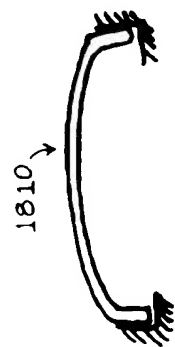


FIG. 18B

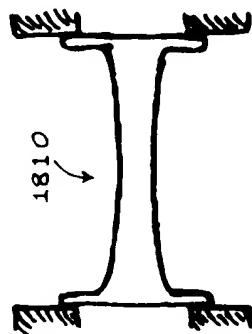


FIG. 18C

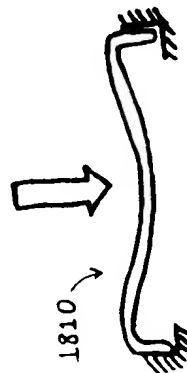


FIG. 18D

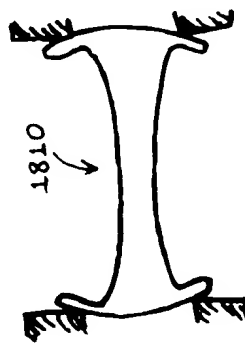


FIG. 18E

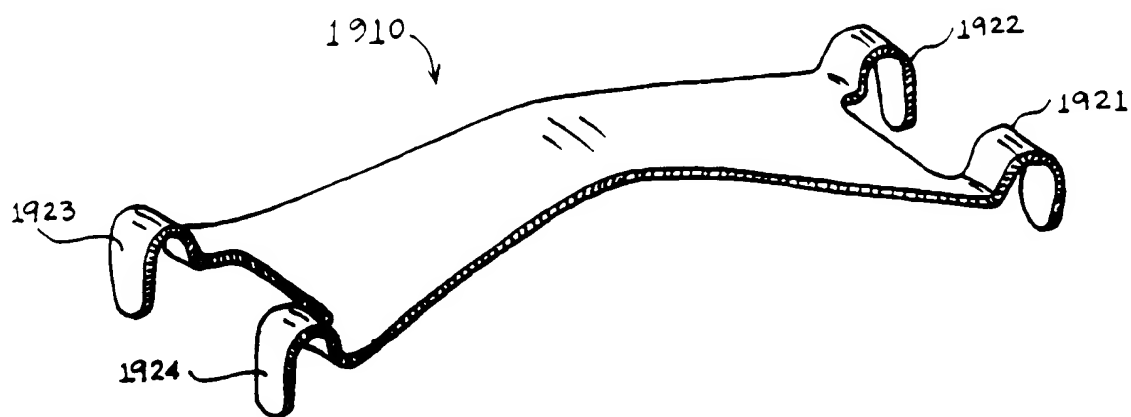


FIG. 19A

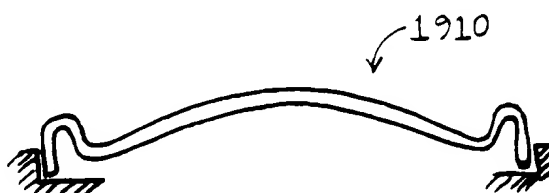


FIG. 19B

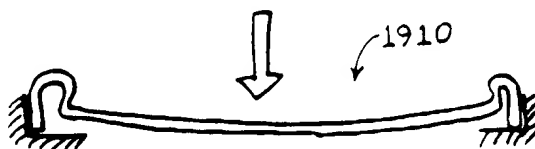


FIG. 19C

FIG. 1 is a cross-sectional view of a device 2010. The device includes a substrate 2030, a layer 2021, and a layer 2022. A gap 2025 is formed between the layers. The device is shown in a cross-sectional view with hatching indicating different materials.

FIG. 20A

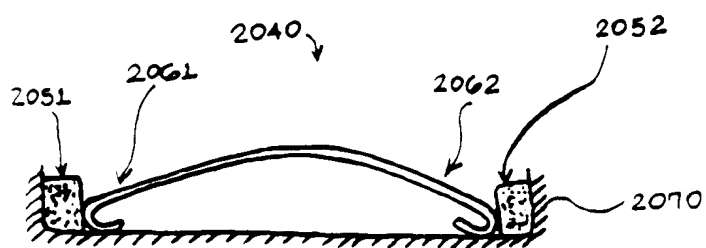


FIG. 20B